

Title (en)
SEMICONDUCTOR WAFER POD

Title (de)
HALBLEITERSCHEIBESCHALE

Title (fr)
NACELLE POUR PLAQUETTE DE SEMI-CONDUCTEUR

Publication
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Application
EP 01931496 A 20010306

Priority

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Abstract (en)
[origin: EP1139390A1] A semiconductor wafer pod comprises a measurement sensor (305) arranged within its housing (109) facing onto a surface of a wafer to be accommodated in the pod. The pod can be connected to the conventional load-port of a semiconductor wafer manufacturing tool. Thereby, measurement data can be collected immediately after wafer processing without a need to transport the wafer. The invention enables a cost-effective development of tool-integrated metrology. <IMAGE>

IPC 8 full level
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